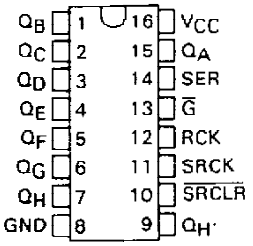
SN54LS595, SN54LS596, SN74LS595, SN74LS596
8-BIT SHIFT REGISTERS WITH OUTPUT LATCHES

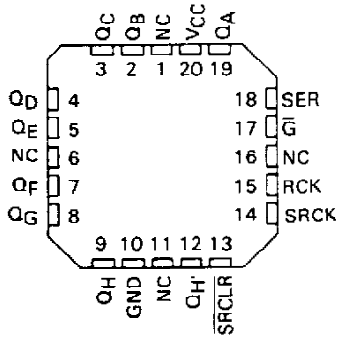
SDLS006 D2634, JANUARY 1981 - REVISED MARCH 1988

- 8-Bit Serial-In, Parallel-Out Shift Registers with Storage
- Choice of 3-State ('LS595) or Open-Collector ('LS596) Parallel Outputs
- Shift Register Has Direct Clear
- Accurate Shift Frequency: DC to 20 MHz

SN54LS595, SN54LS596 . . . J OR W PACKAGE
SN74LS595, SN74LS596 . . . N PACKAGE
(TOP VIEW)



SN54LS595, SN54LS596 . . . FK PACKAGE
(TOP VIEW)



NC - No internal connection

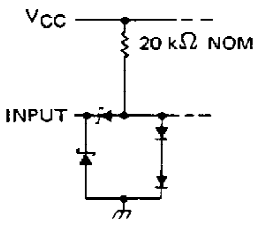
description

These devices each contain an 8-bit serial-in, parallel-out shift register that feeds an 8-bit D-type storage register. The storage register has parallel 3-state ('LS595) or open-collector ('LS596) outputs. Separate clocks are provided for both the shift register and the storage register. The shift register has a direct-overriding clear, serial input, and serial output pins for cascading.

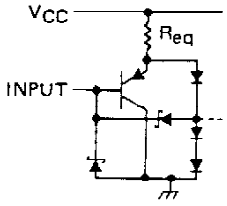
Both the shift register and storage register clocks are positive-edge triggered. If the user wishes to connect both clocks together, the shift register state will always be one clock pulse ahead of the storage register.

schematics of inputs and outputs

EQUIVALENT OF SERIAL INPUT

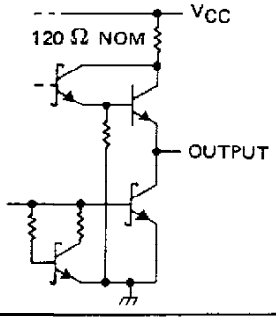


EQUIVALENT OF ALL OTHER INPUTS

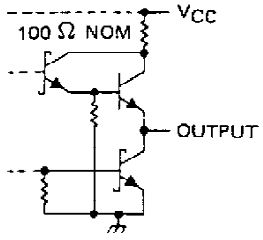


RCK, SRCK: R_{eq} = 10 kΩ NOM
ALL OTHER: R_{eq} = 13 kΩ NOM

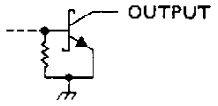
TYPICAL OF Q_H' OUTPUTS



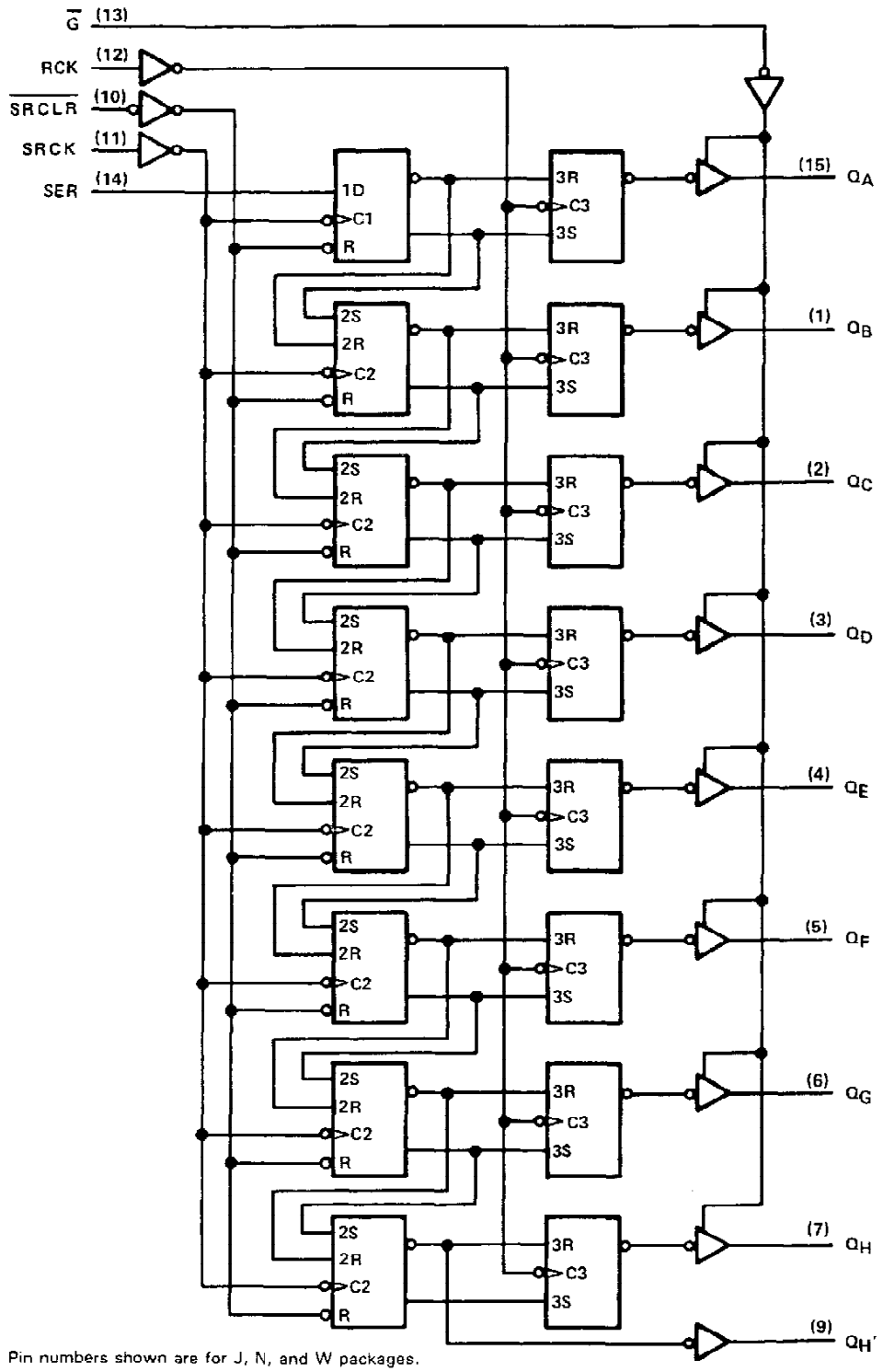
TYPICAL OF ALL OTHER OUTPUTS ('LS595)



TYPICAL OF ALL OTHER OUTPUTS ('LS596)

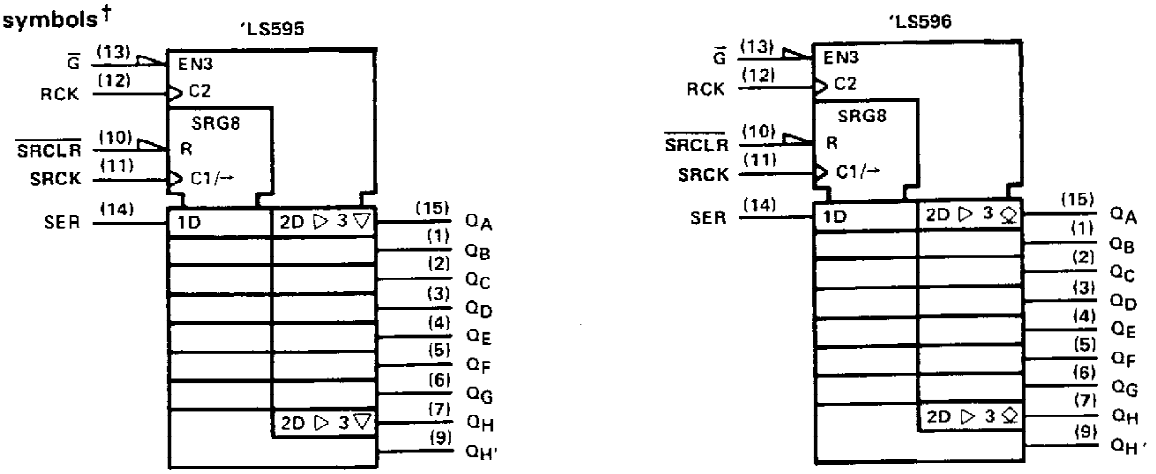


logic diagram (positive logic)



Pin numbers shown are for J, N, and W packages.

logic symbols†



†These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.
Pin numbers shown are for J, N, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage . . . . . 7 V
Off-state output voltage . . . . . 5.5 V
Operating free-air temperature range: SN54LS595, SN54LS596 . . . . . −55°C to 125°C
SN74LS595, SN74LS596 . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

NOTE 1: Voltage values are with respect to the network ground terminal.

recommended operating conditions

			SN54LS'			SN74LS'			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage		2			2			V
V_{IL}	Low-level input voltage				0.7			0.8	V
V_{OH}	High-level output voltage	Q_A thru Q_H, 'LS596 only			5.5			5.5	V
I_{OH}	High-level output current	Q_H'			−1			−1	mA
		Q_A thru Q_H, 'LS595 only			−1			−2.6	
I_{OL}	Low-level output current	Q_H'			8			16	mA
		Q			12			24	
f_{SRCK}	Shift clock frequency		0		20	0		20	MHz
$t_{w(SRCK)}$	Duration of shift clock pulse		25			25			ns
$t_{w(RCK)}$	Duration of register clock pulse		20			20			ns
$t_{w(\overline{SRCLR})}$	Duration of shift clear pulse, low level		20			20			ns
t_{su}	Setup time	$\overline{SRCLR}$ inactive before SRCK ↑	20			20			ns
		SER before SRCK ↑	20			20			
		SRCK ↑ before RCK ↑ (see Note 2)	40			40			
		$\overline{SRCLR}$ low before RCK ↑	40			40			
t_h	Hold time	SER after SRCK ↑	0			0			ns
T_A	Operating free-air temperature		−55		125	0		70	°C

NOTE 2: This setup time ensures the register will see stable data from the shift-register outputs. The clocks may be connected together, in which case the storage register state will be one clock pulse behind the shift register.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS †		SN54LS'			SN74LS'			UNIT
				MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}		V_{CC} = MIN, I_I = −18 mA				−1.5			−1.5	V
V_{OH}	'LS595 Q	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = MAX	I_{OH} = −1 mA	2.4	3.2					V
			I_{OH} = −2.6 mA				2.4	3.1		
	Q_H'		I_{OH} = −1 mA	2.4	3.2		2.4	3.2		
I_{OH}	'LS596 Q	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = MAX, V_{OH} = 5.5 V				0.1			0.1	mA
V_{OL}	Q	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = MAX	I_{OL} = 12 mA		0.25	0.4		0.25	0.4	V
			I_{OL} = 24 mA					0.35	0.5	
	Q_H'		I_{OL} = 8 mA		0.25	0.4		0.25	0.4	
			I_{OL} = 16 mA					0.35	0.5	
I_{OZH}	'LS595 Q	V_{CC} = MAX, V_{IH} = 2 V, V_{IL} = MAX, V_{OH} = 2.7 V				20			20	μA
I_{OZL}	'LS595 Q	V_{CC} = MAX, V_{IH} = 2 V, V_{IL} = MAX, V_{OH} = 0.4 V				−20			−20	μA
I_I		V_{CC} = MAX, V_I = 7 V				0.1			0.1	mA
I_{IH}		V_{CC} = MAX, V_I = 2.7 V				20			20	μA
I_{IL}	SER	V_{CC} = MAX, V_I = 0.4 V				−0.4			−0.4	mA
	All others					−0.2			−0.2	
I_{OS}§	'LS595 Q	V_{CC} = MAX, V_O = 0 V		−30		−130	−30		−130	mA
	Q_H'			−20		−100	−20		−100	
I_{CCH}	'LS595	V_{CC} = MAX, All possible inputs grounded, All outputs open			33	50		33	50	mA
	'LS596				30	45		30	45	
I_{CCL}	'LS595				42	65		42	65	mA
	'LS596				36	55		36	55	
I_{CCZ}	'LS595				44	65		44	65	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.
§ Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	'LS595			'LS596			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
t_{PLH}	SRCK ↑	Q_H'	R_L = 1kΩ, C_L = 30 pF		12	18		14	21	ns
t_{PHL}					17	25		20	30	ns
t_{PLH}	RCK ↑	Q_A thru Q_H	R_L = 667 Ω, C_L = 45 pF		12	18		28	42	ns
t_{PHL}					24	35		24	35	ns
t_{PZH}	$\overline{G}$ ↓	Q_A thru Q_H			20	30				ns
t_{PZL}					25	38				ns
t_{PHZ}	$\overline{G}$ ↑	Q_A thru Q_H	R_L = 667 Ω, C_L = 5 pF		20	30				ns
t_{PLZ}					25	38				ns
t_{PLH}	$\overline{G}$ ↑	Q_A thru Q_H	R_L = 667 Ω, C_L = 45 pF					40	60	ns
t_{PHL}	$\overline{G}$ ↓	Q_A thru Q_H						25	38	ns
t_{PHL}	$\overline{SRCLR}$ ↓	Q_H'	R_L = 1 kΩ, C_L = 30 pF		24	35		24	35	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
5962-8671701EA	Active	Production	CDIP (J) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8671701EA SNJ54LS595J
5962-8671701FA	Active	Production	CFP (W) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8671701FA SNJ54LS595W
5962-8671701FA	Active	Production	CFP (W) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8671701FA SNJ54LS595W
SN54LS595J	Active	Production	CDIP (J) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54LS595J
SN54LS595J	Active	Production	CDIP (J) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54LS595J
SN74LS595D	Obsolete	Production	SOIC (D) | 16	-	-	Call TI	Call TI	0 to 70	LS595
SN74LS595D	Obsolete	Production	SOIC (D) | 16	-	-	Call TI	Call TI	0 to 70	LS595
SN74LS595DR	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS595
SN74LS595DR	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS595
SN74LS595N	Active	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74LS595N
SN74LS595N	Active	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74LS595N
SNJ54LS595J	Active	Production	CDIP (J) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8671701EA SNJ54LS595J
SNJ54LS595J	Active	Production	CDIP (J) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8671701EA SNJ54LS595J
SNJ54LS595W	Active	Production	CFP (W) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8671701FA SNJ54LS595W
SNJ54LS595W	Active	Production	CFP (W) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8671701FA SNJ54LS595W

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

OTHER QUALIFIED VERSIONS OF SN54LS595, SN74LS595 :

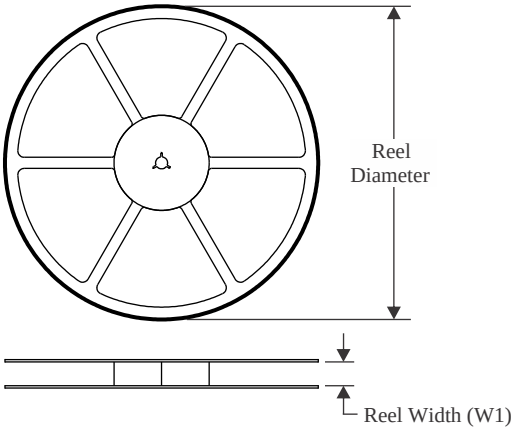
- Catalog : SN74LS595
- Military : SN54LS595

NOTE: Qualified Version Definitions:

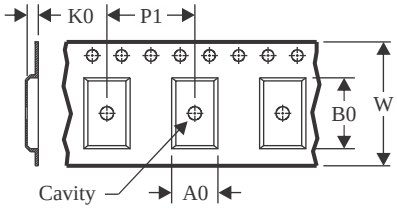
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

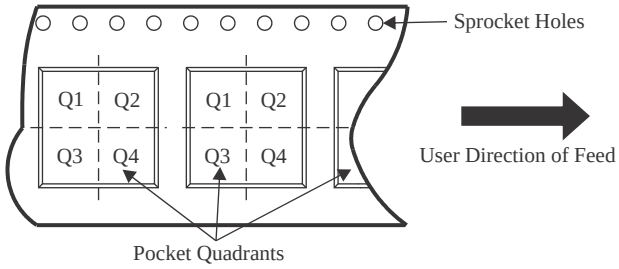


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

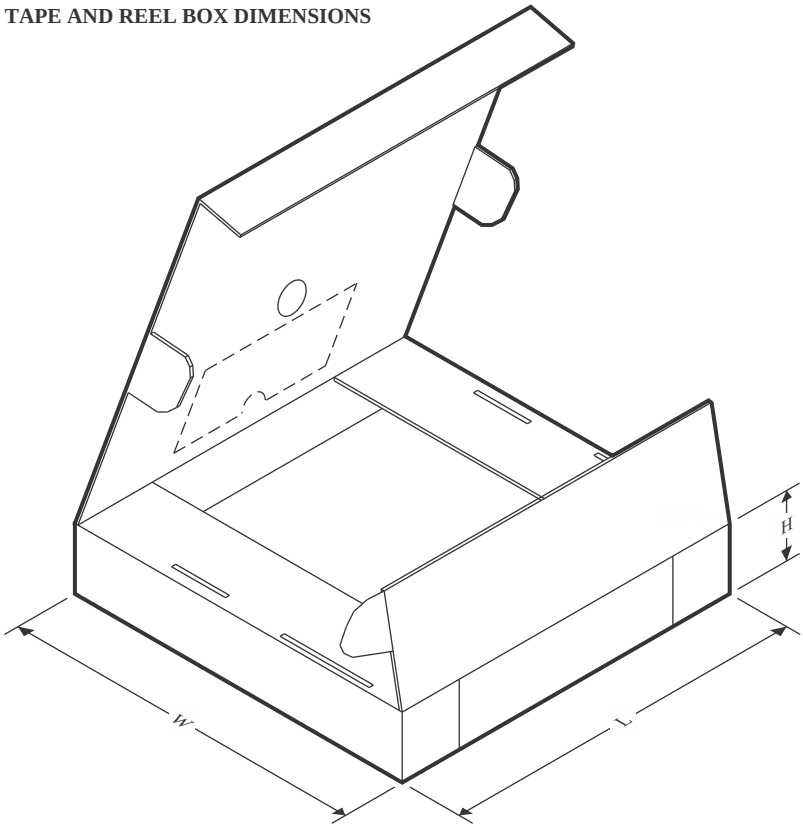
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS595DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

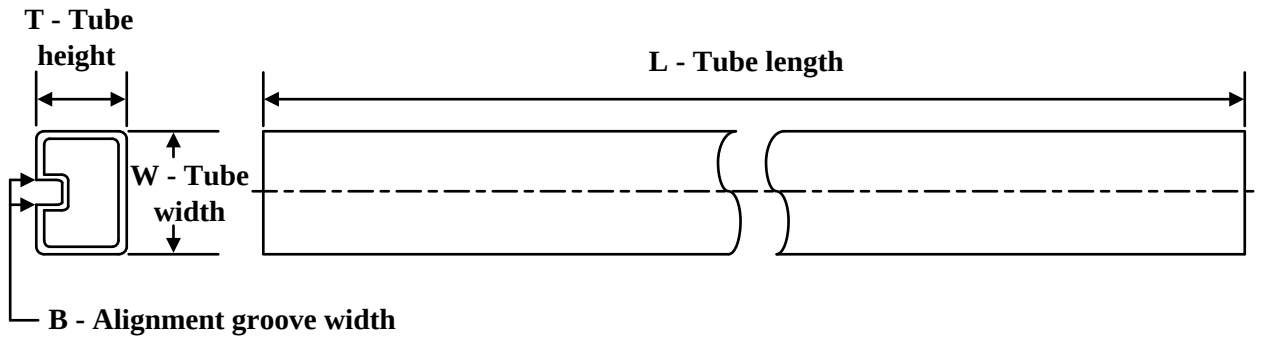
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS595DR	SOIC	D	16	2500	340.5	336.1	32.0

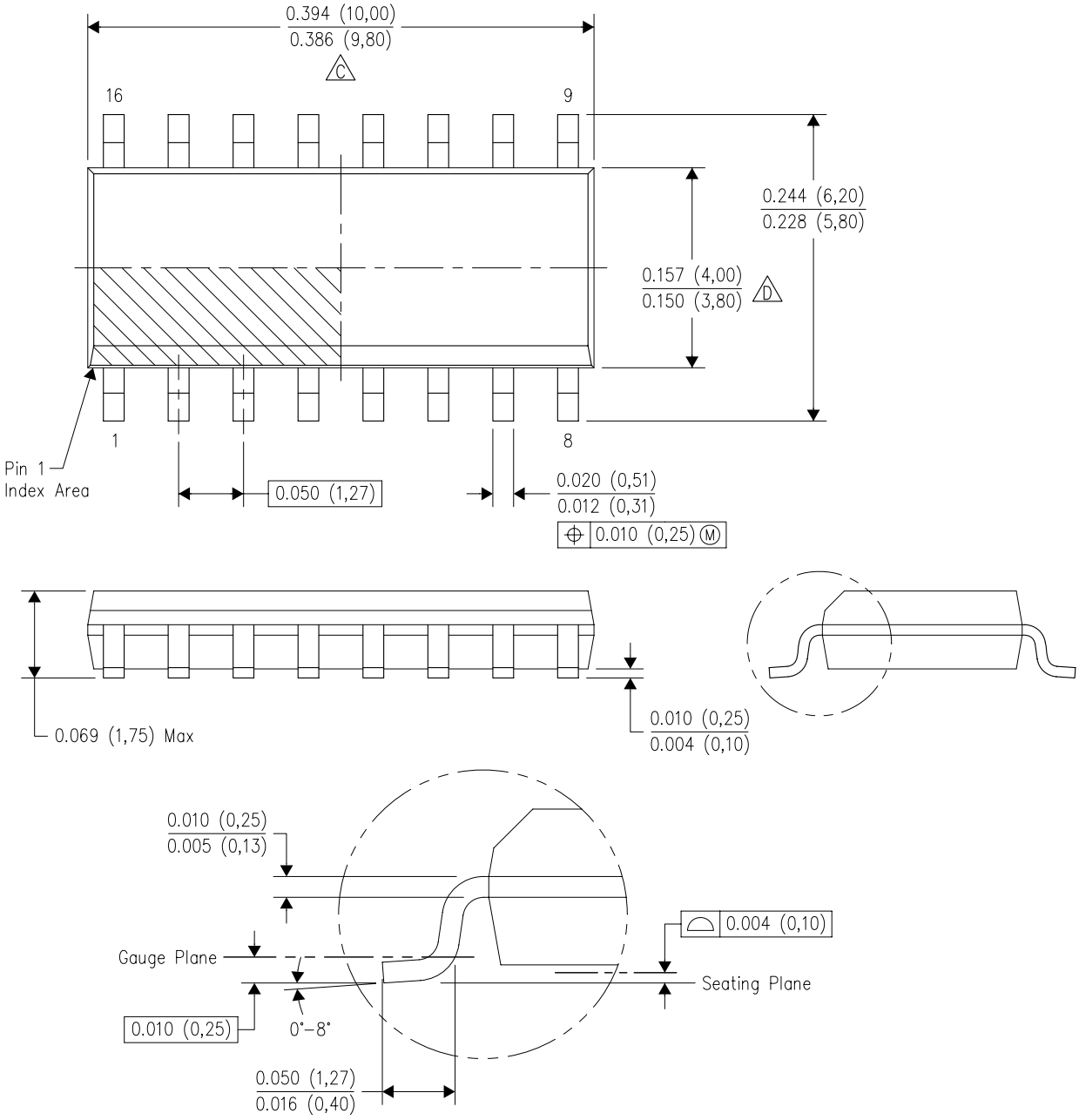
TUBE



*All dimensions are nominal

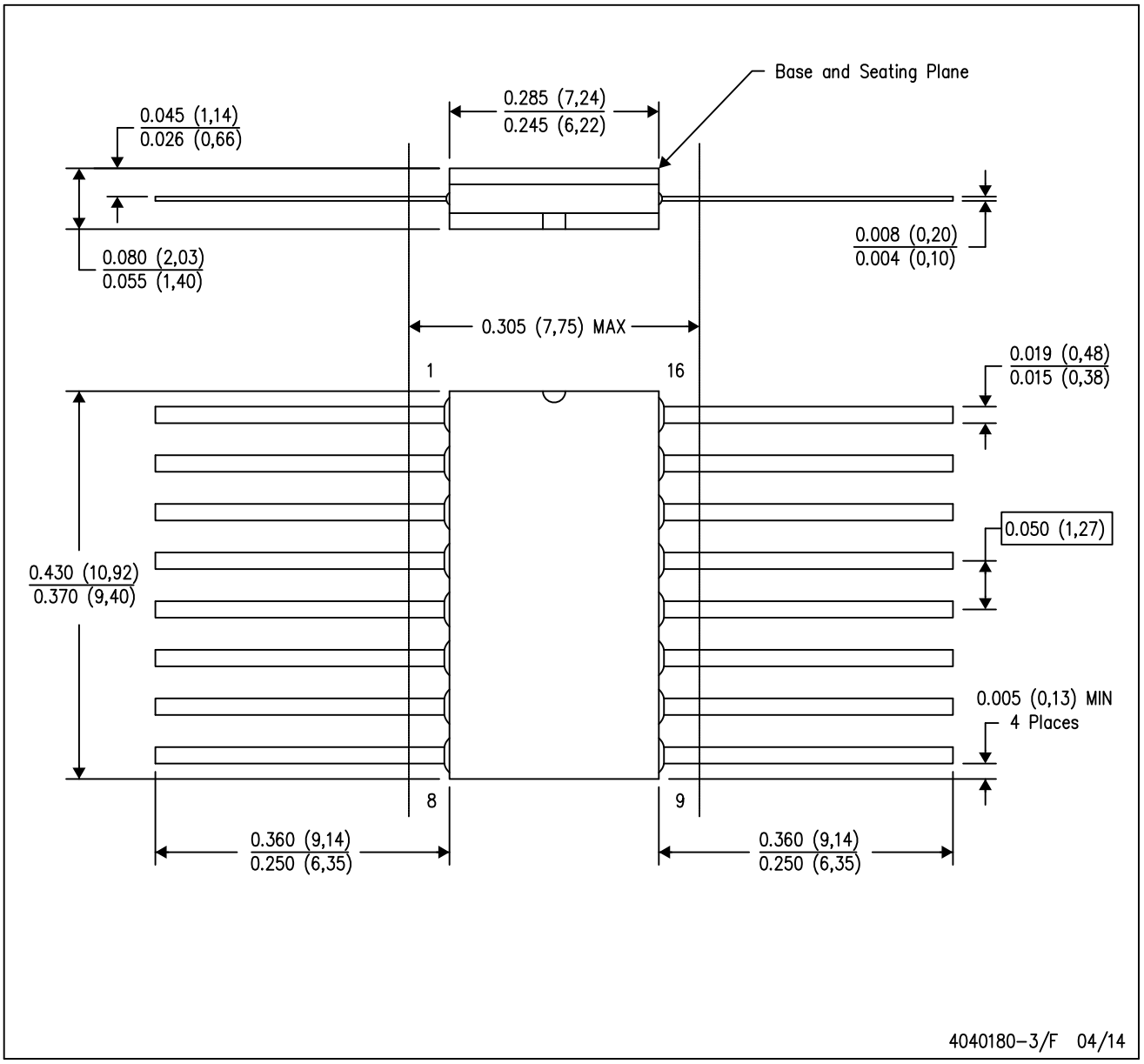
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-8671701FA	W	CFP	16	25	506.98	26.16	6220	NA
SN74LS595N	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS595N	N	PDIP	16	25	506	13.97	11230	4.32
SNJ54LS595W	W	CFP	16	25	506.98	26.16	6220	NA

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AC.

W (R–GDFP–F16) CERAMIC DUAL FLATPACK

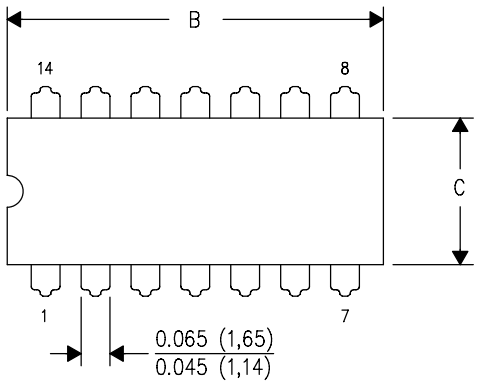


NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP2–F16

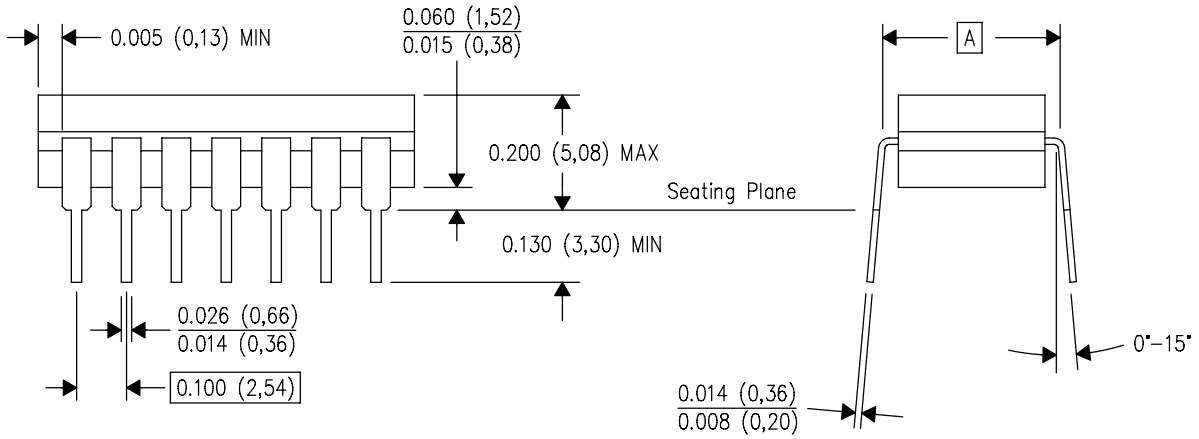
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



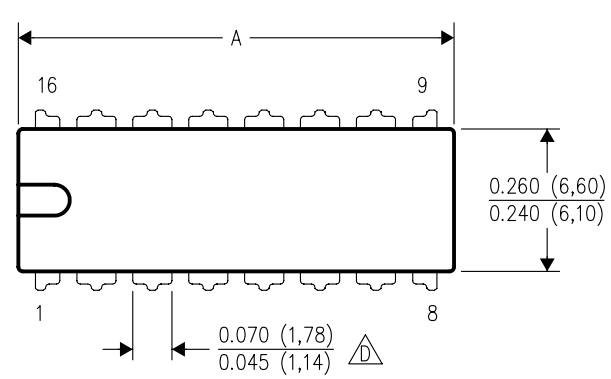
4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

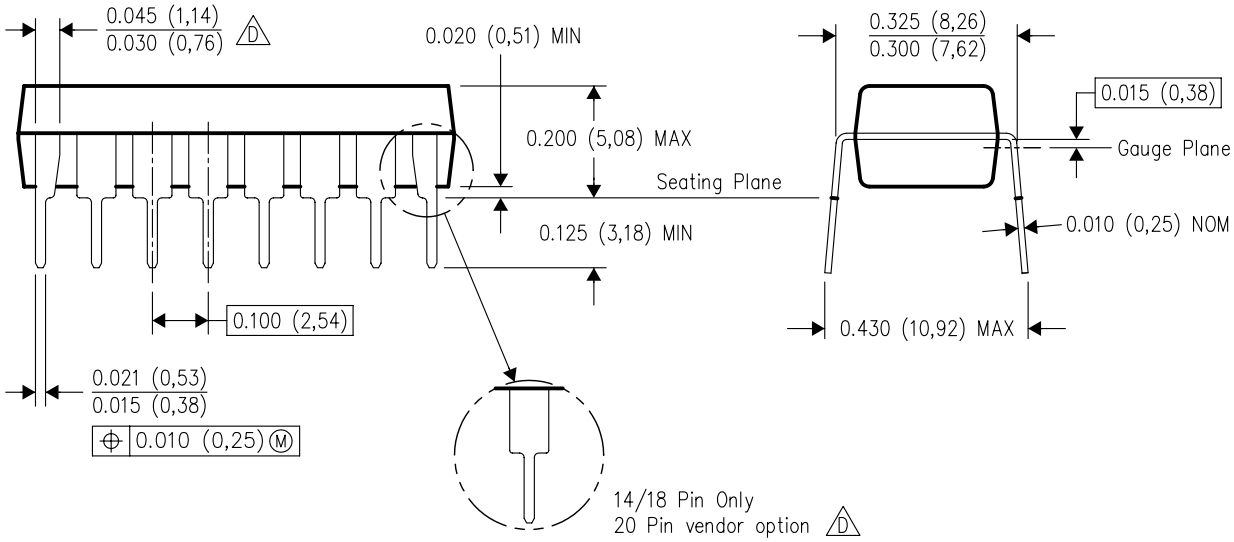
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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